

**PLEASE AMEND THE SPECIFICATION AS FOLLOWS:**

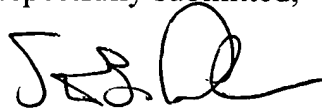
After the title, insert -- This is a division of Patent Application serial number 10/315,534, filing date 12/10/02, Method For Forming A Wafer Level Chip Scale Package, And Package Formed Thereby, assigned to the same assignee as the present invention, which is herein incorporated by reference in its entirety.

**REMARKS**

A reference to the parent case has been added by Preliminary Amendment to this Divisional Patent Application.

The application is believed to be in condition for allowance. Allowance of the subject Patent Application is therefore respectfully requested.

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'S. B. Ackerman', written in a cursive style.

STEPHEN B. ACKERMAN, REG. NO. 37,761